

## Advanced Power MOSFET

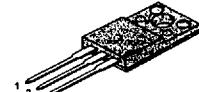
**SSS3N90A**

### FEATURES

- Avalanche Rugged Technology
- Rugged Gate Oxide Technology
- Lower Input Capacitance
- Improved Gate Charge
- Extended Safe Operating Area
- Lower Leakage Current : 25  $\mu$ A (Max.) @  $V_{DS}$  = 900V
- Low  $R_{DS(ON)}$  : 4.679  $\Omega$  (Typ.)

$BV_{DSS} = 900 \text{ V}$   
 $R_{DS(on)} = 6.2 \Omega$   
 $I_D = 2 \text{ A}$

TO-220F



1.Gate 2. Drain 3. Source

### Absolute Maximum Ratings

Symbol	Characteristic	Value	Units
$V_{DSS}$	Drain-to-Source Voltage	900	V
$I_D$	Continuous Drain Current ( $T_c=25^\circ\text{C}$ )	2	A
	Continuous Drain Current ( $T_c=100^\circ\text{C}$ )	1.3	
$I_{DM}$	Drain Current-Pulsed ①	12	A
$V_{GS}$	Gate-to-Source Voltage	$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy ②	286	mJ
$I_{AR}$	Avalanche Current ①	2	A
$E_{AR}$	Repetitive Avalanche Energy ①	3.5	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$ ③	1.5	V/ns
$P_D$	Total Power Dissipation ( $T_c=25^\circ\text{C}$ )	35	W
	Linear Derating Factor	0.28	W/ $^\circ\text{C}$
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
	Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5-seconds	300	

### Thermal Resistance

Symbol	Characteristic	Typ.	Max.	Units
$R_{\theta_{JC}}$	Junction-to-Case	--	3.57	$^\circ\text{C}/\text{W}$
	Junction-to-Ambient	--	62.5	

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# SSS3N90A

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## Electrical Characteristics ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	900	—	—	V	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$
$\Delta \text{BV}/\Delta T_J$	Breakdown Voltage Temp. Coeff.	—	1.13	—	V/°C	$\text{I}_D=250\mu\text{A}$ See Fig 7
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	2.0	—	3.5	V	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=250\mu\text{A}$
$\text{I}_{\text{GSS}}$	Gate-Source Leakage, Forward	—	—	100	nA	$\text{V}_{\text{GS}}=30\text{V}$
	Gate-Source Leakage, Reverse	—	—	-100		$\text{V}_{\text{GS}}=-30\text{V}$
$\text{I}_{\text{DSS}}$	Drain-to-Source Leakage Current	—	—	25	$\mu\text{A}$	$\text{V}_{\text{DS}}=900\text{V}$
		—	—	250		$\text{V}_{\text{DS}}=720\text{V}, \text{T}_C=125^\circ\text{C}$
$\text{R}_{\text{DS(on)}}$	Static Drain-Source On-State Resistance	—	—	6.2	Ω	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=1\text{A}$ ④*
$\text{g}_{\text{fs}}$	Forward Transconductance	—	1.78	—	—	$\text{V}_{\text{DS}}=50\text{V}, \text{I}_D=1\text{A}$ ④
$\text{C}_{\text{iss}}$	Input Capacitance	—	590	770	pF	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=25\text{V}, f=1\text{MHz}$ See Fig 5
$\text{C}_{\text{oss}}$	Output Capacitance	—	55	65		
$\text{C}_{\text{rss}}$	Reverse Transfer Capacitance	—	22	28		
$t_{\text{d(on)}}$	Turn-On Delay Time	—	16	40	ns	$\text{V}_{\text{DD}}=450\text{V}, \text{I}_D=3\text{A},$ $\text{R}_G=16\Omega$ See Fig 13 ④ ⑤
$t_r$	Rise Time	—	26	60		
$t_{\text{d(off)}}$	Turn-Off Delay Time	—	47	105		
$t_f$	Fall Time	—	24	60		
$\text{Q}_g$	Total Gate Charge	—	28	37	nC	$\text{V}_{\text{DS}}=720\text{V}, \text{V}_{\text{GS}}=10\text{V},$ $\text{I}_D=3\text{A}$ See Fig 6 & Fig 12 ④ ⑤
$\text{Q}_{\text{gs}}$	Gate-Source Charge	—	5.5	—		
$\text{Q}_{\text{gd}}$	Gate-Drain( "Miller" ) Charge	—	11.9	—		

## Source-Drain Diode Ratings and Characteristics

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
$\text{I}_s$	Continuous Source Current	—	—	2	A	Integral reverse pn-diode in the MOSFET
$\text{I}_{\text{SM}}$	Pulsed-Source Current ①	—	—	12	A	
$\text{V}_{\text{SD}}$	Diode Forward Voltage ④	—	—	1.4	V	$\text{T}_J=25^\circ\text{C}, \text{I}_s=2\text{A}, \text{V}_{\text{GS}}=0\text{V}$
$t_r$	Reverse Recovery Time	—	380	—	ns	$\text{T}_J=25^\circ\text{C}, \text{I}_F=3\text{A}$
$\text{Q}_{rr}$	Reverse Recovery Charge	—	1.9	—	$\mu\text{C}$	$d\text{I}_F/dt=100\text{A}/\mu\text{s}$ ④

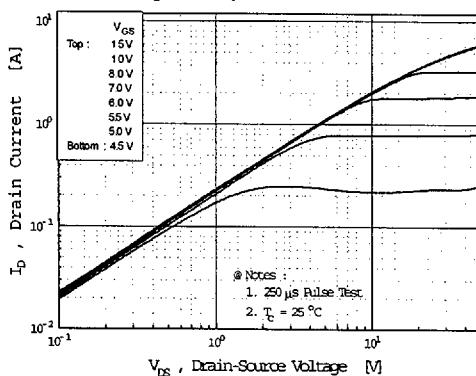
### Notes :

- Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature
- $L=135\text{mH}, \text{I}_{As}=2\text{A}, \text{V}_{DD}=50\text{V}, R_g=27\Omega$ , Starting  $T_J=25^\circ\text{C}$
- $\text{I}_{sd} \leq 3\text{A}, d\text{I}/dt \leq 90\text{A}/\mu\text{s}, \text{V}_{DD} \leq \text{BV}_{DSS}$ , Starting  $T_J=25^\circ\text{C}$
- Pulse Test : Pulse Width =  $250\mu\text{s}$ , Duty Cycle  $\leq 2\%$
- Essentially Independent of Operating Temperature

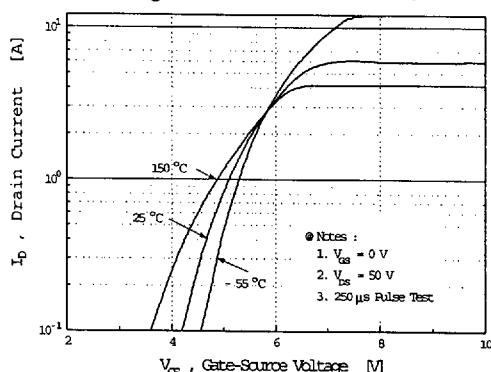
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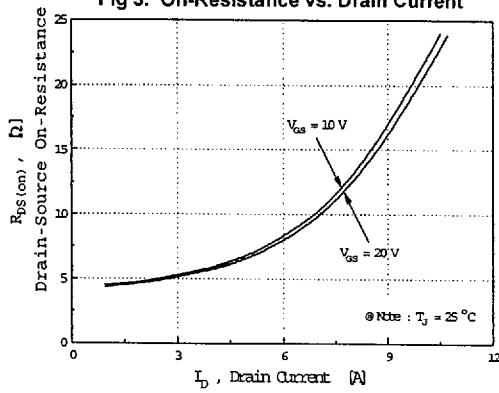
**Fig 1. Output Characteristics**



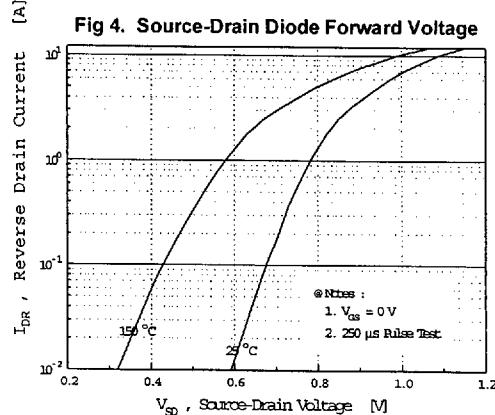
**Fig 2. Transfer Characteristics**



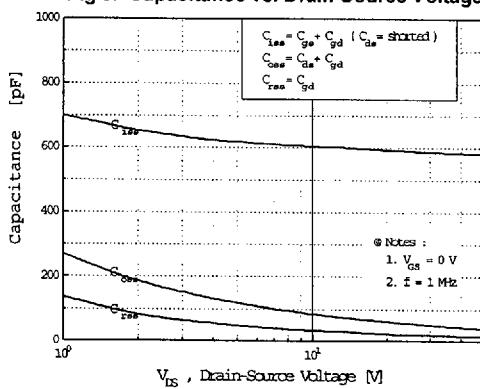
**Fig 3. On-Resistance vs. Drain Current**



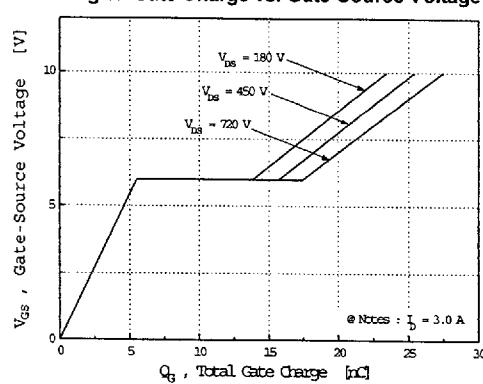
**Fig 4. Source-Drain Diode Forward Voltage**



**Fig 5. Capacitance vs. Drain-Source Voltage**



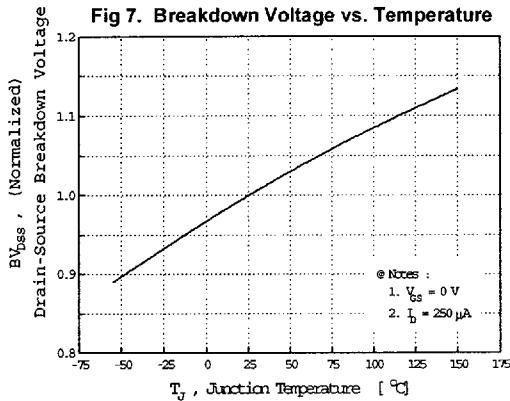
**Fig 6. Gate Charge vs. Gate-Source Voltage**



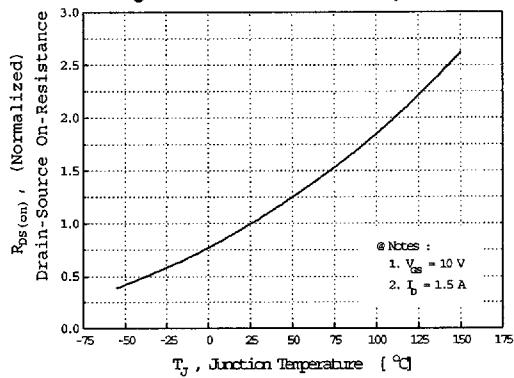
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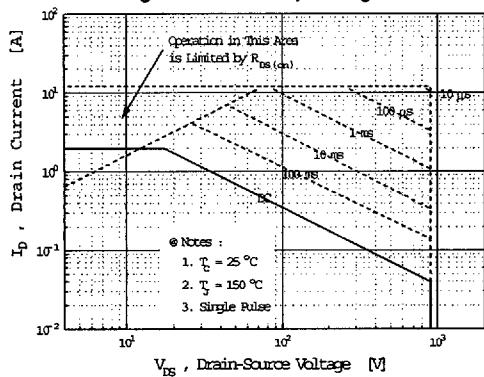
**Fig 7. Breakdown Voltage vs. Temperature**



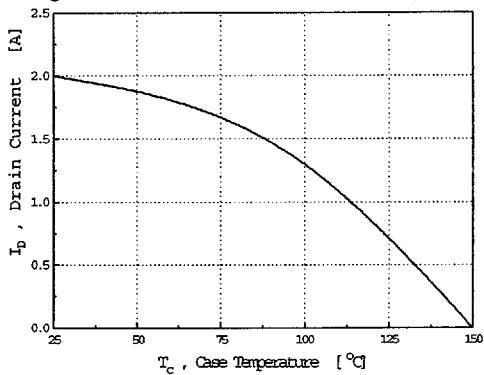
**Fig 8. On-Resistance vs. Temperature**



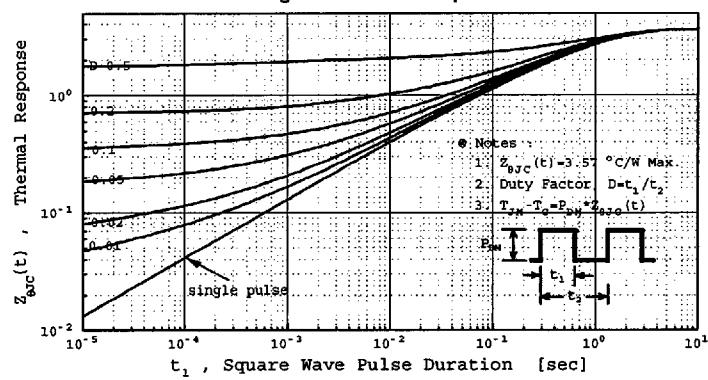
**Fig 9. Max. Safe Operating Area**



**Fig 10. Max. Drain Current vs. Case Temperature**



**Fig 11. Thermal Response**



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Fig 12. Gate Charge Test Circuit & Waveform

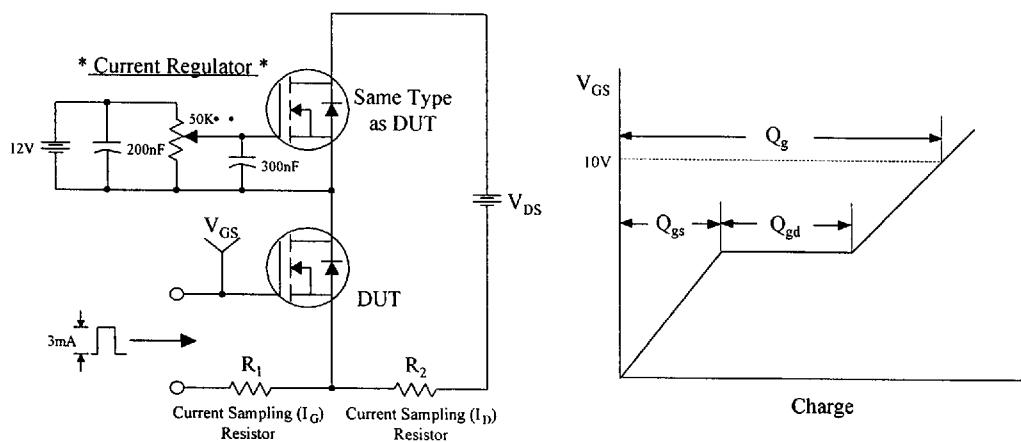


Fig 13. Resistive Switching Test Circuit & Waveforms

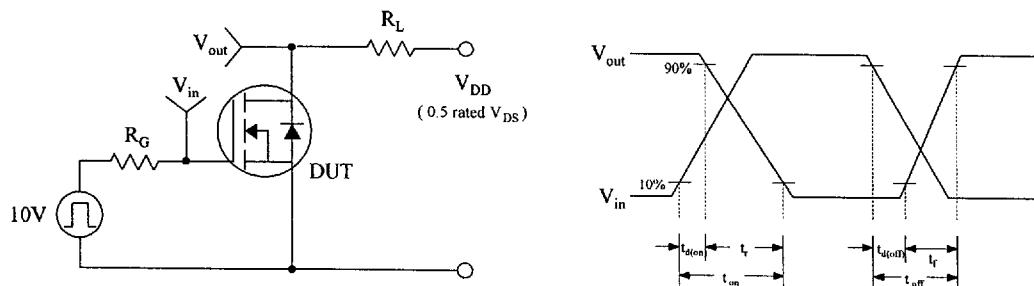
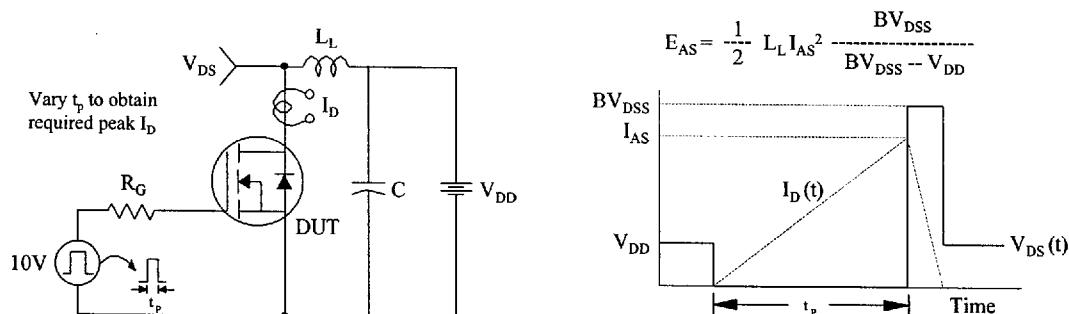


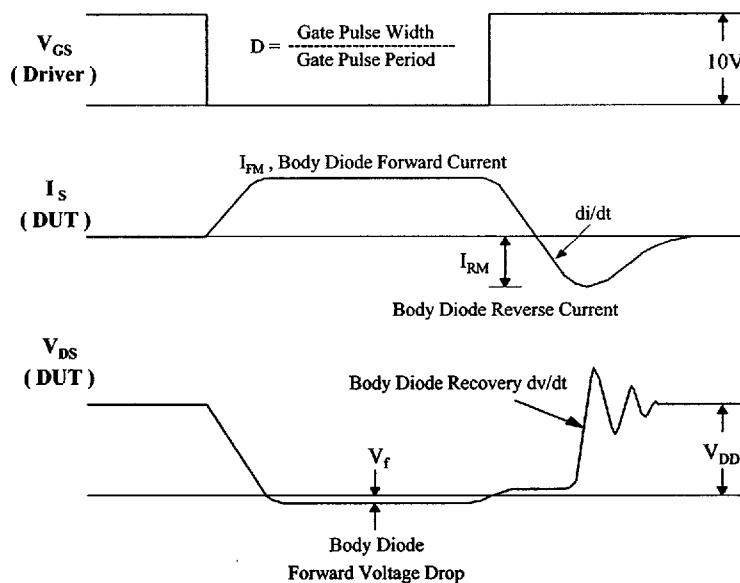
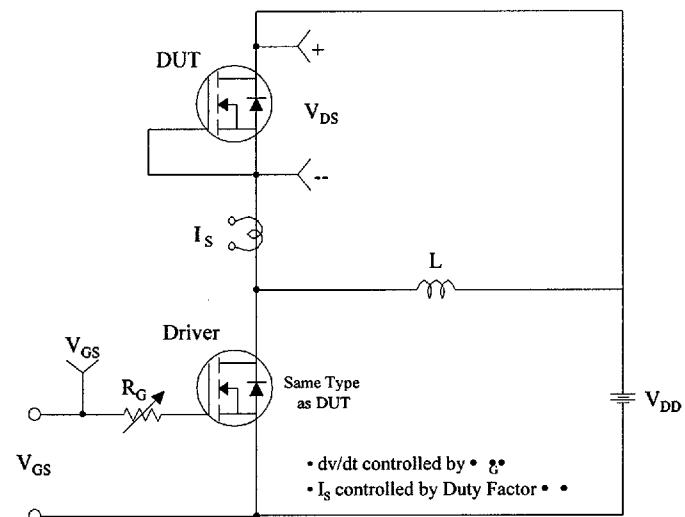
Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms



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Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



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